

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
FEROZ MOHAMMAD	04/19/2018
SRINIVASA ARAVAMUDHAN	04/13/2018
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
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City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15938110
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ATTORNEY DOCKET NUMBER:	(D148064-US) 1884.414US1
NAME OF SUBMITTER:	NOREEN L WELLS
SIGNATURE:	/Noreen L Wells/
DATE SIGNED:	05/01/2018
Total Attachments: 3	
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Atty Ref/Docket No.: (D148064-US) 1884.414US1

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1. Name of conveying party(ies):

Feroz Mohammad, Srinivasa Aravamudhan

Additional name(s) of conveying party(ies) attached?

Yes No

3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: April 19, 2018, April 13, 2018

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054

Country: United States of America

Additional name(s) & address(es) attached? Yes
 No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

Serial No. 15/938,110

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Josef Hoffmann

Address:

Schwegman Lundberg & Woessner, P.A.
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Minneapolis, Minnesota 55402--0938

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 0.00

Enclosed

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9. Statement and signature.

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Josef Hoffmann/Reg. No. 56,203

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Date

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PATENT
REEL: 045684 FRAME: 0892

Intel Docket No.: D148064-US
 SLW Reference No.: 1884.414US1

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

< Feroz Mohammed, Srinivasa Aravamudan > FM
 < Srinivasa Aravamudan, Feroz Mohammed >

Date 04/19/2018

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

PIN THROUGH SOLDER INTERCONNECT AND METHODS

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on March 28, 2018 as

United States of America Application Number 15/938,110

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors,

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assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

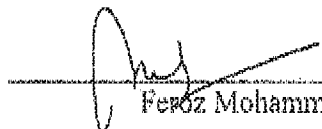
covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Srinivasa Aravamudhan

APR 13 2018

Date Signed



Feroz Mohammad

APR 19, 2018

Date Signed